

Miniature Glass Passivated Single Phase Surface Mount Bridge Rectifiers
Reverse Voltage 50 to 1000 Volts Forward Current 0.5 Ampere

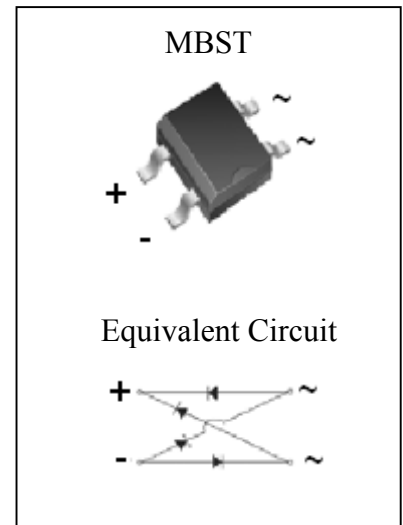
MB05ST05 thru MB10ST05

Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Save space on printed circuit boards
- Glass passivated chip junction
- High surge overload rating: 30A peak

Mechanical Data

- Case: Molded plastic body over passivated junctions
- Terminals: Pure tin plated, solderable per MIL-STD-750 method 2026
- High temperature soldering guaranteed : 260°C/10 seconds, 0.375”(9.5mm) lead length, 5lbs(2.3kg) tension
- Mounting position: Any.
- Weight: 0.22gram, 0.078 oz.



Maximum Ratings and Electrical Characteristics

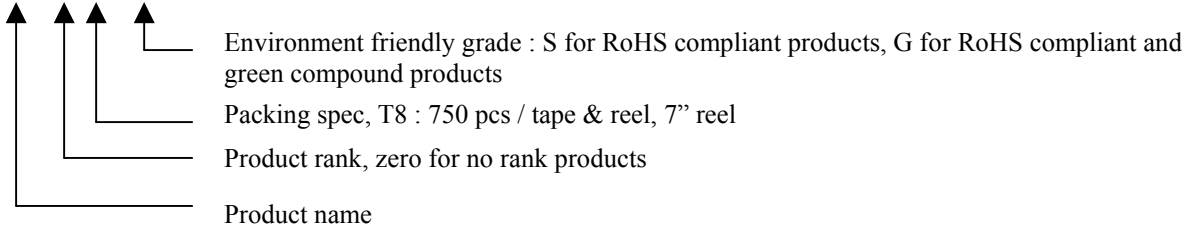
(Rating at 25°C ambient temperature unless otherwise specified.)

Parameter	Symbol	Type							Units
		MB05S T05	MB1S T05	MB2S T05	MB4S T05	MB6S T05	MB8S T05	MB10S T05	
Repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum instantaneous forward voltage drop per leg at 0.4A	V _F	1							V
Maximum average forward output rectified current @T _a =40°C	I _{F(AV)}	0.5							A
Peak forward surge current @8.3ms single half sine wave superimposed on rated load (JEDEC method)	I _{FSM}	30							A
Maximum DC reverse current at rated DC blocking voltage per leg	I _R	T _A =25°C							μA
		T _A =100°C							
Typical thermal resistance per leg	R _{θJA}	75							°C/W
	R _{θJL}	20							
	R _{θJC}	24							
Typical diode junction capacitance @f=1MHz and applied 4V reverse voltage	C _J	25							pF
Operating junction and storage temperature range	T _J ; T _{stg}	-55 ~ +150							°C



Ordering Information

Device	Package	Shipping
MBXXST05-0-T8-X	MBST (Pb-free lead plating and halogen-free package)	750 pcs / tape & reel



Characteristic Curves

FIG 1-TYPICAL FORWARD CURRENT DERATING CURVE

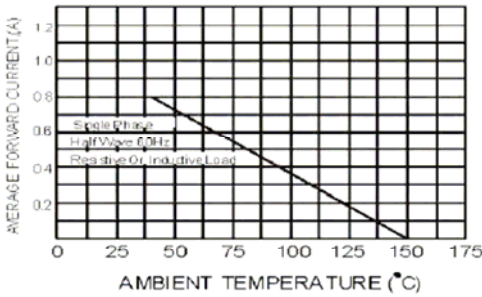


FIG 2-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

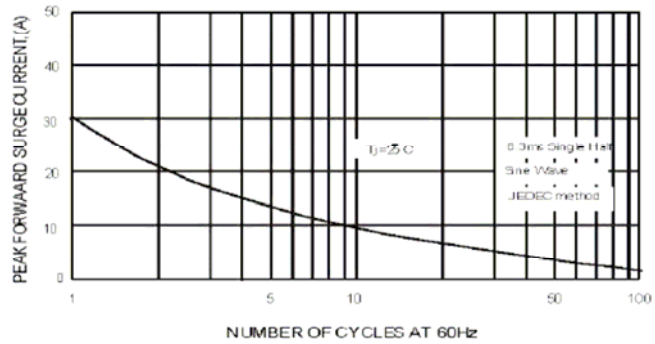


FIG.3-TYPICAL FORWARD CHARACTERISTICS

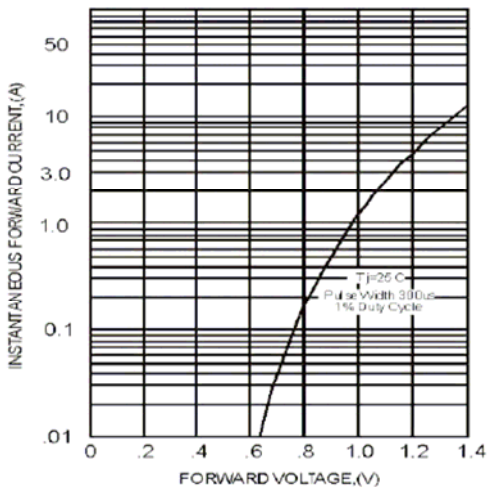
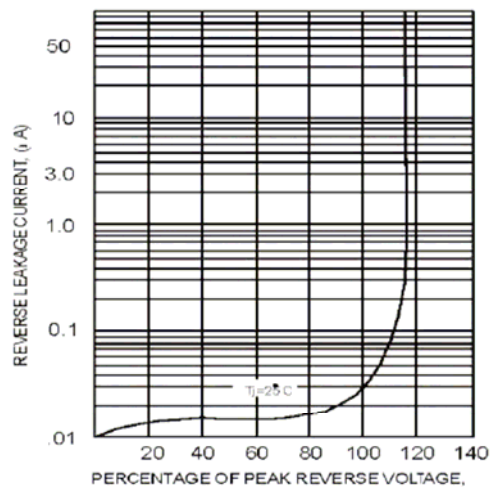
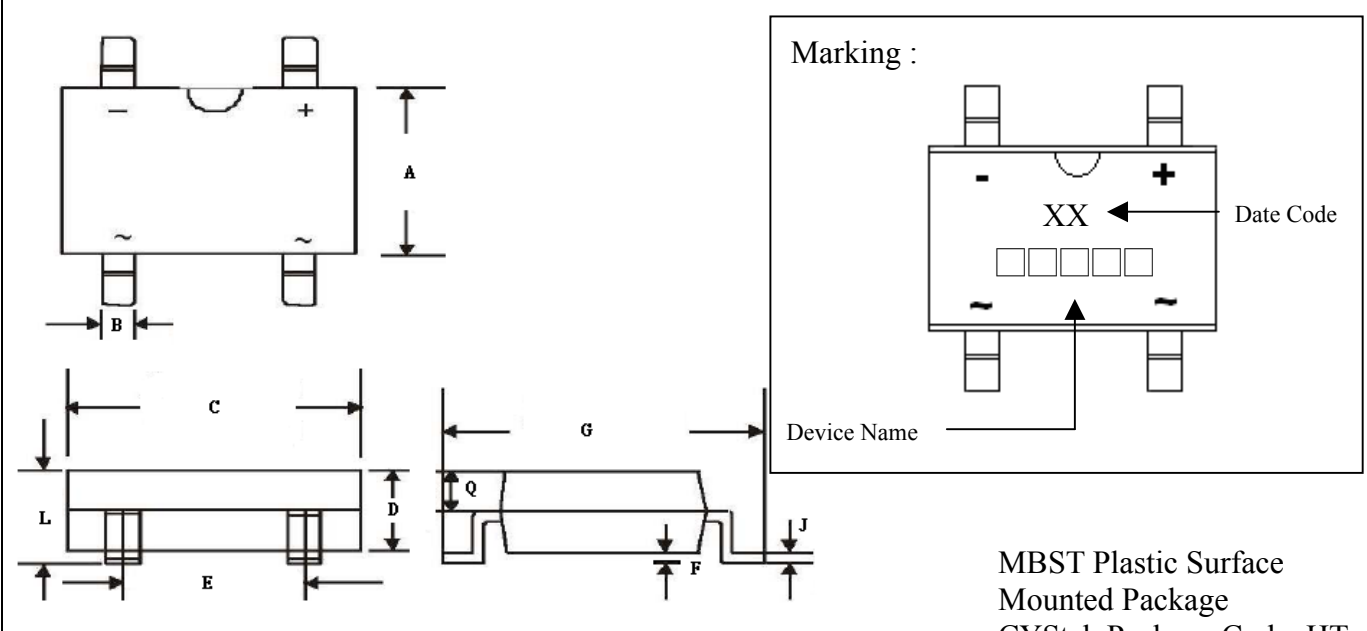


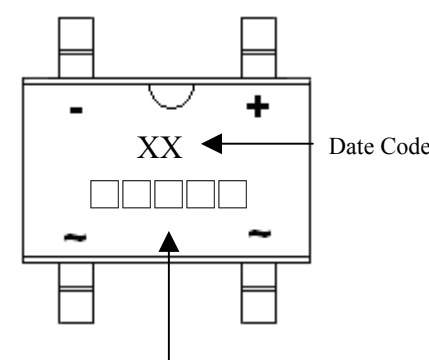
FIG.4-TYPICAL REVERSE CHARACTERISTICS



MBST Dimension



Marking :



MBST Plastic Surface Mounted Package
 CYStek Package Code: HT

Type	MB05ST05	MB1ST05	MB2ST05	MB4ST05	MB6ST05	MB8ST05	MB10ST05
Marking	MB05S	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.165	0.181	4.200	4.600	F	-	0.008	-	0.200
B	0.023	0.031	0.600	0.800	G	-	0.275	-	7.000
C	0.177	0.193	4.500	4.900	J	0.006	0.010	0.150	0.250
D	0.049	0.057	1.250	1.450	L	-	0.650	-	1.650
E	0.900	0.106	2.300	2.700	Q	0.024	0.028	0.600	0.700

Notes : 1.Controlling dimension : millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : Pure tin plated.
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0.

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